

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Trident Microsystems, Inc.	09/30/2006

RECEIVING PARTY DATA

Name:	Trident Microsystems (Far East) Ltd.
Street Address:	Ugland House
Internal Address:	South Church Street
City:	Grand Cayman
State/Country:	CAYMAN ISLANDS

PROPERTY NUMBERS Total: 8

Property Type	Number
Application Number:	09384809
Application Number:	09443054
Application Number:	09442868
Application Number:	10038277
Application Number:	10132746
Application Number:	10318618
Application Number:	11472588
Application Number:	11489091

CORRESPONDENCE DATA

Fax Number: (650)833-2001

*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*

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PATENT

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500224547

CH \$320.00 09384809

Address Line 4: East Palo Alto, CALIFORNIA 94303

ATTORNEY DOCKET NUMBER:

348162-25

NAME OF SUBMITTER:

David L. Alberti

**Total Attachments: 5**

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**ASSIGNMENT AGREEMENT**  
**TRIDENT MICROSYSTEMS, INC. — TRIDENT MICROSYSTEMS (FAR EAST) LTD.**

This ASSIGNMENT AGREEMENT ("Agreement") is effective as of September 30, 2006 ("Effective Date") by and between Trident Microsystems, Inc., a Delaware corporation, located at 3408 Garrett Drive, Santa Clara, California 95054 ("TMI"), and Trident Microsystems (Far East) Ltd., Cayman Islands corporation located at Ugland House, South Church Street, Grand Cayman, Cayman Islands ("TMFE") (collectively, the "Parties" and individually "Party").

**RECITALS**

WHEREAS, TMFE owns world-wide economic rights with respect to certain intellectual property relating to the digital media semiconductor business;

WHEREAS, TMI previously transferred all economics rights and interest in certain patents relating to the digital media semiconductor business to TMFE;

WHEREAS, TMI retained record title to the patents, which are set forth in Exhibit 1 ("Patents");

WHEREAS, the Parties desire to transfer record title of the Patents to TMFE; and

WHEREAS, the Parties agree that the transfer of record title of certain patents to TMFE is not intended to transfer any economic rights from TMI to TMFE.

NOW, THEREFORE, for good and valuable consideration, the Parties agree as follows:

**ARTICLE 1**  
**DEFINITIONS**

Section 1.1 "Affiliate" of a Party means any entity controlled by, controlling, or under common control with such Party where "control" in any of the foregoing forms means ownership, either direct or indirect, of more than fifty percent (50%) of the equity interest entitled to vote for the election of directors or equivalent governing body.

Section 1.2 "Patents" means the patents listed in Exhibit A ("Patents") attached hereto.

**ARTICLE 2**  
**ASSIGNMENT**

Section 2.1 Assignment. TMI hereby irrevocably and absolutely assigns its record title to the Patents to, and in favor of, TMFE, including record title to all Letters Patent and applications for Letters Patent or similar forms of protection of the United States of America, and all other patents and applications for Letters Patent in whatsoever countries, including all divisional, renewal, substitute, continuation and convention applications claiming priority to or

based in whole or in part upon the Patents, or upon related applications, and any and all Letters Patent, reissues and extensions of Letters Patent or similar forms of protection granted upon the Patents and related applications.

Section 2.2 Further Assistance. TMI agrees to perform all acts reasonably deemed necessary or desirable by TMFE to permit and assist TMFE, at TMFE's expense, in perfecting title to Patents. Such acts may include, but are not limited to, execution of documents and assistance or cooperation in the registration of applicable patents or other legal proceedings. In the event that TMFE is unable for any reason whatsoever to secure a signature to any document it believes is reasonably required in order to apply for or execute any patent or other application (including improvements, renewals, extensions, continuations, divisions or continuations in part thereof), TMI hereby irrevocably designates and appoints TMFE and its duly authorized officers and agents as TMI's agents and its attorneys-in-fact to act for and on its behalf and instead of it, to execute and file any such application and to do all other lawfully permitted acts to further the issuance of patents with the same legal force and effect as if executed by TMFE.

### **ARTICLE 3 REPRESENTATIONS AND WARRANTIES**

Section 3.1 Organization and Authority. TMI warrants that it is a corporation duly organized and existing in good standing under the laws of Delaware. TMI represents and warrants that TMI has full power and authority to make and enter into this Agreement.

Section 3.2 Ownership. TMI represents and warrants that TMI is the sole and exclusive holder of title to the Patents. TMI further represents and warrants that the execution and delivery of this Agreement will transfer to and vest in TMFE good, valid and marketable title to the Patents free and clear of all security interests, liens, encumbrances, charges or other restrictions.

### **ARTICLE 4 GENERAL PROVISIONS**

Section 4.1 Assignment. This Agreement shall be binding upon and inure to the benefit of the successors and assigns of the Parties.

Section 4.2 Counterparts. This Agreement may be executed in any number of counterparts, each of which, when executed and delivered, shall be deemed to be an original, but all counterparts shall together constitute one and the same document.

Section 4.3 Governing Law and Jurisdiction. Any questions, claims, disputes or litigation concerning or arising from the Agreement shall be governed by the laws of Delaware without giving effect to the conflicts of laws principles of that state or any nation state. Each of the Parties agrees to submit to the exclusive jurisdiction of the courts in Delaware for any matter arising out of or relating to this Agreement. Notwithstanding the foregoing, in actions seeking to enforce any order or any judgment of any such courts located in Delaware, personal jurisdiction shall be nonexclusive.

Section 4.4 Headings and Construction. The headings in this Agreement are for convenience only and will not be construed to affect the meaning of any provision of this Agreement. Any use of "including" shall also be deemed to mean "including without limitation."

Section 4.5 Legal Expenses. The prevailing Party in any legal proceeding brought by one Party against the other Party and arising out of or in connection with this Agreement shall be entitled to recover its legal expenses, including court costs and reasonable attorney's fees.

Section 4.6 Mutual Drafting. This Agreement is the joint product of the Parties and their respective counsel and each provision hereof has been subject to the mutual consultation, negotiation and agreement of such Parties and counsel and shall not be construed for or against any Party on the basis of authorship thereof.

Section 4.7 Remedies Cumulative. A Party's remedies under this Agreement are cumulative and shall not exclude any other remedy to which the Party may be entitled.

Section 4.8 Severability. If any provision in this Agreement shall be found or be held to be invalid or unenforceable, then the meaning of said provision shall be construed, to the extent feasible, so as to render the provision enforceable, and if no feasible interpretation would save such provision, it shall be severed from the remainder of this Agreement which shall remain in full force and effect unless the severed provision is essential and material to the rights or benefits received by any Party. In such event, the Parties shall use good faith efforts to negotiate a substitute, valid and enforceable provision or agreement that most nearly affects the Parties' intent in entering into this Agreement.

Section 4.9 Taxes. Each Party hereto shall be responsible for any and all taxes levied as a result of the performance of each Party's respective obligations under this Agreement.

By their signatures, the authorized representatives of the Parties acknowledge the Parties' acceptance of this Agreement.

TRIDENT MICROSYSTEMS, INC.

By: \_\_\_\_\_

President

TRIDENT MICROSYSTEMS (FAR EAST) LTD.

By: \_\_\_\_\_

Director

**EXHIBIT 1**  
**PATENTS**

<b>Title</b>	<b>U.S. Patent Application No. / Patent No.</b>	<b>Filing Date</b>
Motion and Edge Adaptive Deinterlacing	09/384,809 / 6,421,090	8/27/1999
User Interface for Control of a Display Device	09/443,054 / 6,552,738	11/18/1999
System and Method for Communicating Digital Data from a Computer System to a Display Device	09/442,868	11/18/1999
Method and System for Single-Chip Integration of 3D Y/C Comb Filter and Interlace-to-Progressive Converter	10/038,277	10/20/2001
Method and System for Motion and Edge-Adaptive Signal Frame Rate Up-Conversion	10/132,746 / 6,975,359	4/25/2002
Method and System for Advanced Edge-Adaptive Interpolation for Interlace-to-Progressive Conversion	10/318,618	12/13/2002
System and Method for Reducing Mosquito Noise in a Digital Image	Not as yet assigned	7/19/2006
Method and Systems for Frame Insertion in a Digital Display System	11/472,588	6/22/2006

**FOREIGN PATENTS**

<b>Title</b>	<b>Country/ Application No./ Patent No.</b>	<b>Filing Date</b>
Motion and Edge Adaptive Deinterlacing	TW 154899	8/25/2000
Motion and Edge Adaptive Deinterlacing	EP 009549419.3	8/25/2000
Motion and Edge Adaptive Deinterlacing	CN ZL00814934.8	8/25/2000

<b>Title</b>	<b>Country/ Application No./ Patent No.</b>	<b>Filing Date</b>
Method and System for Single-Chip Integration of 3D Y/C Comb Filter and Interlace-to-Progressive Converter	CN 02147211.4	10/18/2002
Method and System for Single-Chip Integration of 3D Y/C Comb Filter and Interlace-to-Progressive Converter	TW 91124126	10/18/2002
Method and System for Single-Chip Integration of 3D Y/C Comb Filter and Interlace-to-Progressive Converter	JP 2002-305922	10/21/2002
Method and System for Single-Chip Integration of 3D Y/C Comb Filter and Interlace-to-Progressive Converter	KR 10-2002-0064051 / 532021	10/19/2002
Method and System for Motion and Edge-Adaptive Signal Frame Rate Up-Conversion	CN 03140765.X	4/24/2003
Method and System for Motion and Edge-Adaptive Signal Frame Rate Up-Conversion	EP 03252652.7	4/25/2003
Method and System for Advanced Edge-Adaptive Interpolation for Interlace-to-Progressive Conversion	JP 2003-148269	5/26/2003
Method and System for Advanced Edge-Adaptive Interpolation for Interlace-to-Progressive Conversion	KR 10-2003-0032985 / 563023	5/23/2003
Method and System for Advanced Edge-Adaptive Interpolation for Interlace-to-Progressive Conversion	TW 92113324 / I 227632	5/16/2003
Method and System for Single-Chip Integration of 3D Y/C Comb Filter and Interlace-to-Progressive Converter	CN 200310124636.9 / ZL200310124636.9	12/12/2003
Method and System for Advanced Edge-Adaptive Interpolation for Interlace-to-Progressive Conversion	JP 2003-414313	12/12/2003
Method and System for Advanced Edge-Adaptive Interpolation for Interlace-to-Progressive Conversion	TW 92134364 / I 231706	12/5/2003